1	Printed electrodes structures as capacitive humidity sensors: A
2	comparison
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12	Abstract- This work discusses about four planar printed capacitive sensors with different
14	geometrical layouts, fabricated by inkjet printing on a flexible substrate and used as
15	humidity sensors. In particular, we show a comparison among interdigitated electrodes,
16	meandered electrodes, spiral electrodes, and serpentine electrodes in terms of fabrication
17	yields, sensitivities to relative humidity as well as thermal drift taking into account
18	frequency dependencies. In addition, numerical simulations have been performed to
19	further investigate the characteristics of these sensors. All sensors present similar
20	behavior in frequency with humidity. Taking into account sensitivity within the same
21	sensing area, the highest value is achieved by serpentine electrodes, followed by spiral
22	electrodes, interdigitated and meandered electrodes, in this order. The best configuration
23	will be dependent on the specific application and its requirements.
24 25	Keywords: interdigitated electrodes; serpentine electrodes; spiral electrodes;
26	meandered electrodes; inkjet printing; capacitive humidity sensors; comparison

27 **1. Introduction**

Capacitive structures are widely used in electronics to address many different applications [1]; they are especially interesting in the field of sensors due to their characteristics, such as low energy consumption, non-intrusive and non-invasive, no radiation and fast response [2, 3]. The most common sensing capacitive structures are the parallel plate (PP) and the interdigitated electrode (IDE). PP is characterized by the simplicity of its geometry and the ease of calculation and modelling. 34 IDE sensors are a particular case of planar capacitive structures where the sensor 35 electrodes are placed in a co-planar plane [4]. The planar structure allows to access the 36 device from only one side [5], which is particularly useful when the access to an material 37 under test (MUT) is limited or the other side should be open to the ambient. The advantage 38 of this kind of structures is the fact that they can be fabricated on a substrate by deposition 39 of a layer without including any step of micromaching. That allows compatibility with 40 any kind of technology. Furthermore, this geometry has been used to fabricate with 41 multiple materials and following different manufacturing process, from integration in 42 semiconductor dices to printing on flexible substrates [6-8]. This additional feature makes 43 planar capacitive sensors an attractive option for applications in material characterization 44 [5], non-destructive testing (NDT) [9], proximity/displacement measurement [10], 45 intelligent human interfacing [11], and imaging [12, 13]. Many efforts have been devoted 46 to the theoretical modelling of the planar capacitive structures. Igreja et al. [14] presented 47 a theoretical model of the capacitance of IDE structure. These capacitors have also been 48 simulated using different simulations tools [15-17]. Some authors have analysed other 49 designs such as spiral electrodes and concentric rings in order to improve the performance 50 of this design [7, 18, 19]. Other structures such as rectangular-shaped [20] and comb-51 shaped sensor arrays [21] were studied, showing that desired linearity and sensitivity can 52 be achieved by the optimal selection of a set of structural parameters. Zeothout et al. [22] 53 analyzed a rectangular shaped planar sensor using a numerical method and also compared 54 its performance according to different material properties and boundary conditions.

55 On the other hand, flexible electronic devices manufactured by printing techniques have 56 become increasingly attractive thanks to their feasibility of large scale processing, 57 potential low-cost per surface area and mechanical flexibility. Great advances have been 58 achieved in the design of flexible and printed humidity sensors [23-26] as well as sensors 59 for other gases and vapours [27-29]. The classical transduction mechanism of these 60 humidity sensors is capacitive due to the requirement of low energy consumption, in 61 particular, through changes in the electrical permittivity of some structural layer of the 62 capacitor or the dielectric thickness. Different printed techniques have been used to manufacture capacitive printed devices and different approaches have been followed to 63 64 add the sensing capability into the capacitor. The most common strategy has been to 65 deposit a sensing layer over the electrodes [16, 30, 31] such as cellulose acetate butyrate 66 (CAB), poly(methyl methacrylate) (PMMA) or polyvinylchloride (PVC), among others. 67 Another possibility has been to select a flexible substrate as sensing element saving 68 fabrication steps, in this sense, polyimide [26] and photographic paper [25] have already 69 been used. One of the main interfering factors to obtain an accurate humidity 70 measurement is temperature. In order to compensate this dependence, several strategies 71 have been already described such as differential measurements with reference capacitors 72 (not sensitive to humidity) [32], including additional temperature sensors [33, 34] or using 73 a sensitive layer with very low thermal drift [35, 36]. This latter alternative does not 74 require additional devices, and therefore, less area and energy is consumed.

75 In this work, we will show the design, fabrication and characterization as humidity sensor 76 of four different coplanar electrodes comparing and contrasting their characteristics. In 77 this regard, we present the design, fabrication and characterization of capacitive humidity 78 sensors which uses the flexible substrate as sensitive element. These capacitors have been 79 printed with silver nanoparticles ink by inkjet-printing on a polyimide thin film. In the 80 context, this paper discusses planar printed capacitive sensors in terms of fabrication 81 vields, sensitivity to relative humidity as well as thermal drift taking into account 82 frequency dependencies. Further investigations of the sensor designs have been carried out using a numerical method. The differences among these planar capacitive sensors are 83 84 pointed out as well as their advantages and disadvantages of the different electrodes 85 designs.

86 2. Materials and methods

87 A. Fabrication process

The DMP-2831TM Dimatix printer (Fujifilm Dimatix Inc, Santa Clara, USA) was used for inkjet printing. The selected materials were an ink of silver nanoparticles (U5603 SunTronic Technology, San Diego, USA) on a polyimide substrate (Kapton® HN with 75 μ m of thickness, DupontTM). Table 1 shows the main properties of the used ink and substrate, respectively.

According to the manufacturer of the substrate, the relationship between the relative permittivity (ε_r) and the relative humidity (RH) is given by:

95
$$\varepsilon_r = 3.05 + 0.008 \cdot RH(\%)$$
 at 1 kHz, 23 °C (1)

96 The first step before printing was to prepare the substrate removing all traces of particles 97 with a cleaning process to ensure the best quality and to avoid failed printings. First, the 98 substrate was immersed in acetone for 2 min to remove dust on the surface, and then was 99 submerged in propanol about 2 min to remove the acetone. After that, the substrate was 100 washed with purified water to eliminate the propanol and finally was dried at 120°C for 101 5 min. During the printing process the substrate temperature was fixed at 40°C and a drop 102 space of 25 µm was settled for 50 µm landed diameter drops. Finally, a sintering step is 103 carried out at 120 °C for 60 min.

104 In order to know the thickness of the printed layer, the theoretical model given in [37] 105 has been used. According to this model, the amount of used ink is 22.7 nl for one printed 106 layer with a thickness of 460 nm. With that printing and curing conditions, the resistivity 107 of the conductive electrodes were $23 \pm 2 \mu \Omega \cdot cm$ [37]. The fabrication time is much shorter 108 than in the case of other sensors because no other sensing layer was needed [16, 30, 31]. 109 The fabrication process is also simplified because it only required printing one layer on 110 one side of the substrate. In a previous work, we demonstrated that thickness layer does 111 not contribute significantly to capacitance and therefore the definition of electrodes by only one printed layer is enough for a proper sensor performance [35]. A matrix of twenty 112 113 capacitors of each type was fabricated in order to test the reproducibility of the process.

114 B. Physical and electrical characterization

The geometrical characterization, the roughness of printed patterns as well as the thickness of the patterns have been measured using a Wyko NT1100 Optical Profiling System (VEECO, Tucson, AZ, USA), and a Dektak XTTM Stimulus Surface Profiling System (Bruker Corporation, Conventry, UK).

119 The AC electrical characterization for the different fabricated capacitors has been 120 performed by measuring their capacitance and dissipation factor, using the four-wire 121 measurement technique with a precision Impedance Analyser 4294A and an impedance 122 probe kit (4294A1) (Agilent Tech., Santa Clara, CA, USA). The excitation voltage 123 applied in all measurements was $V_{DC} = 0$ and $V_{AC} = 500$ mV. The frequency sweep of 124 analysis was from 100 kHz to 10 MHz. In all prototypes, one of the end sides has been 125 enlarged to facilitate its connection to any analyser. A SMA (SubMiniature version A) 126 male connector has been glued to these ends points using silver-filled epoxy EPO-TEK[®] 127 H20E (Epoxy Technology, Inc., Billerica, USA). A complete compensation method has been implemented to eliminate the contribution of parasitic capacitances by measuring
several commercial capacitances placed in the same configuration as the devices under
test with the 16034G surface mount device (SMD) Test Fixture (Agilent Tech., Santa
Clara, CA, USA).

132 The stationary humidity and temperature responses of the sensors have been measured in 133 a climatic chamber VCL 4006 (Vötsch Industrietechnik GmbH, Germany). The humidity 134 deviation in time was $\pm 1\%$ to $\pm 3\%$, whereas the temperature deviation in time was ± 0.3 135 $^{\circ}$ C to $\pm 0.5 ^{\circ}$ C. The data acquisition and analysis have been automated using Labview 136 2012 software (National Instruments Corporation, Texas, USA). Due to the slow response 137 of the mentioned climatic chamber, the dynamic response has been measured in a 138 customized humidity measurements set-up $(9 \times 3 \text{ cm}^2)$, which automatically controls wet 139 and dry airflow inside a small gas cell at room temperature. Two LCR-meters (HP 4284L 140 and Agilent E4980A, Agilent Tech., Santa Clara, CA, USA) have been used to measure 141 the corresponding capacitance values at a frequency of 100 kHz every 5 s. Capacitance 142 and time measurements of the printed sensors have been controlled and recorded using 143 the software Labview 2012. RH and temperature measurements have been also registered 144 by a commercial sensor (SHT15, Sensirion AG, Switzerland) in order to verify the data 145 given by the chambers' displays. In all cases, the capacitors have been placed in the 146 middle of the climatic chambers allowing the atmosphere interaction in both faces of the 147 sensors, printed and non-printed.

148 C. Electrodes designs

We have analysed four different electrodes configurations as capacitive sensor. In this section, we present the geometry of each device, pointing out the dimensions and areas of the fabricated capacitors.

152 Interdigitated electrodes

First, interdigitated electrodes (Figure 1a) have been studied. As we mentioned before, this structure is the most common one to develop planar capacitive sensors thanks to its compromise between ease of manufacturing and performance. Table 2 presents the dimensions of the modelled IDE sensor, resulting in a designed area of 11.65 mm² (L = 1.85 mm × W = 6.3 mm) and a capacitance of 1.97 pF at dry atmosphere calculated by numerical simulation.

159 Meandered electrodes

160 Meandered electrodes have been developed as capacitive sensor as shown in Figure 1b.

161 Although this geometry shows at first glance lower contact area than the previous ones, 162 it could result interesting in some applications, as we will describe in the following 163 section. The designed sensor structure area is 89.0 mm² (L = 4.00 mm x W = 22.25 mm)

- 164 following specifications shown in Table 3 and the numerical capacitance is 3.14 pF at dry
- 165 atmosphere.

166 Spiral electrodes

Another studied structure has been the spiral electrodes. This structure has been previously reported by [18, 38] to achieve a high compactness. In this case, the electrodes are placed as a coil inductor (Figure 1c). Table 4 shows the physical dimensions of the

- 170 modelled spiral capacitor with a total area of 5.52 mm² (L = 2.35 mm x W = 2.35 mm)
- 171 and numerical capacitance of 0.91 pF at dry atmosphere.

172 Serpentine electrodes

Finally, this periodic electrode structure consists of a combination of meandering and interdigitated electrodes in a serpentine-shaped geometry [36] (Figure 1d). Serpentine electrodes (SRE) were previously used as electrode guard of IDE structures [39], impedance sensor for conformal skin hydration monitoring [40] or a three phase electrode array for AC electro-osmotic flow pumping [41]. SRE geometry is describe in Table 5, covering a total area of 11.65 mm² (L = 1.85 mm × W = 6.3 mm). The numerical capacitance of this structure is 2.26 pF at dry atmosphere.

180 **3. Results and discussion**

181 A. Simulation results

With the aim of structure optimizations and after different simulations varying the fundamental geometrical parameters, we have used COMSOL Multiphysics 4.2a (www.comsol.com, COMSOL, Inc. USA). This is a powerful interactive tool for solving problems based on partial differential equations with the finite element method. This software has previously been used to calculate distributions of potential field in this kind of structures [17, 34]. The equations solved in the determination of the capacitance in each finite element are:

189
$$-\nabla \varepsilon_0 \varepsilon_r \nabla V = \rho \qquad (\text{Eq. 2})$$

190
$$\boldsymbol{D} = \varepsilon_0 \varepsilon_r \mathbf{E}$$
 (Eq. 3)

191 where ρ is the charge density, D is the electric displacement, and E is the electric field. 192 The electrostatic energy density needed to charge a capacitor is equal to that energy of 193 the electrostatic field, and is given by:

194
$$W_e = \int_{\Omega} DEd\Omega \qquad (Eq. 4)$$

Then, the total capacitance is determined by the integral of the electric energy densitythrough the relation:

197
$$C = \frac{2}{V_{port}^2} \int_{\Omega} W_e d\Omega \qquad (Eq. 5)$$

198 where V_{port} is the value of the applied voltage in the port of the sensor. The other electrode 199 is connected to ground. The electrical parameters of the substrate given by the 200 manufacturer and the printed and cured conductive silver ink according to our 201 characterization were included in the numerical simulator [37].

202 The main results obtained are summarized as follow:

- If the sensing strategy is based on a sensitive substrate, the influence of the
 electrode thickness is virtually negligible in comparison with the other
 geometrical features. This result has been appreciated in all simulated structures.
- Keeping fixed gap between electrodes and their width, the bigger the structure,
 the bigger its capacitance and therefore, the sensitivity is enhanced.
- Regarding the capacitance in the same substrate area, simulations show that SRE
 presents the greatest value followed by spiral electrodes, IDE and meandered
 electrodes.

211 B. Physical characterization

Twenty samples of each type of electrode configuration were fabricated with just one printed layer. To experimentally check the simulated layouts, the replicas of each structure were physically characterized. According to a previously developed physical model of thickness layer by inkjet printing [16, 37], the calculated thicknesses are 430 216 nm for one printed layer. The measured dimensions of the structures are presented in 217 Table 6 for IDE and SRE, Table 7 for spiral electrodes and Table 8 for meandered 218 electrodes, showing the differences between measured and modelled dimensions. 219 Uncertainties were calculated as one standard deviation of the experimental data. R_a is 220 the arithmetic average of the absolute values, both of the surface roughness height and R_q 221 is the root mean square (RMS).

In general, predicted and experimental dimensions are quite similar, although the bigger discrepancies are found in electrodes width and interspacing. As explained by Derbi et al. [42], printing electronics techniques present undesirable effects resulting in an inaccuracy on the printed structure, such as wider fingers and narrower inter-spacing. Table V summarizes the main features of each electrode configuration.

227 The yield rate was estimated from the low frequency capacitance measurements of the 228 several replicas of each type of capacitor. During these tests, a preliminary manufacturing 229 yield of 90% was found for IDE (including samples totally and partially broken) and 230 meandered capacitors whereas lower values where found for spiral and serpentines 231 electrodes, about 80%. This lower manufacturing yield is directly associated with the 232 higher complexity of the latter configurations with respect to the former ones. It should 233 be highlighted that in the case of IDE capacitors the device works when there is any 234 broken finger, being the only effect a decreased in the total capacitance. In the other 235 configuration studied, capacitors are totally useless when there is any printing error. 236 Therefore, the manufacturing yield of IDE capacitors would be about 95% if we admit 237 broken fingers. Comparing SRE and spiral electrodes, the manufacturing yield obtained 238 is virtually the same but taking into account that spiral electrodes are about half area of 239 SRE devices, this yield should be lower in the case of spiral electrodes if we have 240 fabricated these capacitors with double area. An easy way to avoid the increase of failure 241 is to connect in parallel this device, so that the equivalent capacitance is equal to the sum 242 of individual values.

243 C. RH Sensitivity and Thermal drift

For five capacitors of each electrode configuration, the capacitances have been measured from 100 kHz to 10 MHz as a function of the relative humidity and temperature. In order to gain a better understanding of the whole sensor responses eliminating the area influence, we have defined the area-normalized partial sensitivities of the capacitance 248 with the relative humidity, $S_{RH}(f)$, and the temperature, $S_T(f)$ as a function of the 249 measurement frequency, f, as:

250
$$S_{RH}(f) \equiv \frac{\partial C(RH)}{A\partial RH} \Big|_{T=cte}$$
(2)

251
$$S_T(f) \equiv \frac{\partial C(T)}{A\partial T} \Big|_{RH=cte}$$
(3)

where A corresponds to the structure area. The humidity response has been calculated in a range from 20% RH to 90% RH at constant temperature of 40 °C, while the thermal drift has been obtained in a range from 20 °C to 50 °C at constant moisture content (50% RH). The RH sweeps were performed in both directions in steps of 10% RH while temperature sweeps were performed in both directions in steps of 5°C.

257 Figure 2 shows the comparison of the sensitivity to relative humidity of each sensor as a 258 function of frequency. All sensors show a similar trend in frequency, a relative higher 259 value at lower frequencies and sensitivity trends to a constant value at higher frequencies. 260 In terms of performance, SRE shows the highest normalized sensitivity values, followed 261 by spiral electrodes and IDE. Meandered electrodes present the lowest value. For 262 example, the normalized RH sensitivity at 1 MHz is 0.44 fF/%RH·mm² for SRE, 0.42 fF/%RH·mm² for spiral electrodes, 0.36 fF/%RH·mm² for IDE and 0.06 fF/%RH·mm² 263 264 for meandered electrodes. Whereas the same sensitivities at 100 kHz is 0.52 fF/%RH·mm² for SRE, 0.48 fF/%RH·mm² for spiral electrodes, 0.38 fF/%RH·mm² for 265 266 IDE and 0.06 fF/%RH·mm² for meandered electrodes. As can be observed, the sensitivity 267 is virtually no affected by frequency in the case of meandered electrodes.

268 Looking at the displacement vector, the highest values are found in all the structures 269 around the edges regions, with SRE and spiral electrodes being the designs that show 270 more area at highest value due to the fact that they present more edges than the other two 271 configurations (see Figure 3). This result can explain the capacitance values obtained. 272 The electric displacement field varies the charge stored between the sensor electrodes 273 and, therefore, alters the inter-electrode capacitance (see Eq. 3 to 5 above). This can be 274 used to infer the properties of the material under test, in this case, the humidity sensitive 275 substrate. These results agree with the study of the capacitance sensitivity as a function 276 of the structure shape by Hu et al. [4] where meandered shapes (interdigitated and spiral 277 electrodes) showed higher sensitivities.

Figure 4 presents the normalized thermal drift of each electrode design. Depending on the specific application and its requirements, we could choose a configuration or another. For example, SRE and spiral electrodes should be selected when sensitivity is a critical factor. In addition, depending on the shape where the sensor in going to be placed could be better the key requirement to select the electrode shape. But these two designs are more complex than the other two and, therefore, their yield rates are lower than the other two configurations.

285 IDE electrodes show the best compromise between sensitivity, area and manufacturing 286 yield. Although meandered electrodes show the lowest performance, this configuration 287 can be very useful to develop more complex sensor configurations such as double sensor 288 as presented in [43]. Furthermore, the distance between electrodes in this latter design 289 can be reduced and the performance could be closer to the other capacitors. In particular, the simulated capacitance obtained is 0.12 pF/mm² when width1 and width2 are 150 µm 290 291 and 250 µm, respectively. This result improves four times the sensitivity obtained by 292 simulations with the fabricated meandered sensor although lower than the capacitance 293 obtained with the other configurations.

294 D. Time response and Time stability

295 The dynamic response of IDE and SRE sensors present a high stability along different 296 measurement cycles and over time. On one hand, the response time can be defined as t =297 τ , corresponding to the 63% of the maximum value of capacitance (reached at 298 equilibrium) for every increasing step of RH. This time is equal to 356 ± 3 s and 350 ± 3 299 s for IDE and SRE, respectively. On the other hand, the response time for desorption, τ' , 300 can be described as the time associated to the 37% of the maximum value of capacitance 301 for every decreasing step of RH; this value is 367 ± 4 s for IDE and 365 ± 4 s for SRE 302 [35, 36]. These values have been calculated as the mean value of the sensor response to 303 changes in RH from 15% to 45%, 15% to 65% and 15% to 85% at room temperature.

These times are virtually the same for both electrode configurations studied. The explanation to these long response times can found in the difference between diffusion rates in the solid substrate used compared to the deposited layers in other similar structures [16, 30]. Although these printed sensors can hardly compete in terms of response time with commercial CMOS-based humidity sensors (SHT15, Sensirion AG, Switzerland) with times smaller than 10 s, this lower performance in response time should 310 not be a problem to use of these printed humidity sensors since humidity is an 311 environmental property that often changes gradually. Furthermore, these times can be 312 easily reduced by using a thinner substrate. Harrey et al. [44] presented a parallel-plate 313 capacitive sensors with several humidity sensitive polymers including polyimide (Kapton 314 HN). Indeed, they showed that the times responses achieved varied from 5 min to 10.5 315 min for Kapton HN depending on the thickness of the film. Anyway, all these sensors as 316 they are presented here could be applied for environmental humidity monitoring, where 317 variations are usually gradual and slow.

Regarding time stability, the IDE and SRE sensors have been measured once a week for more than 6 months and the variation between data has been less than 10 fF in both cases. In order to determine the aging drift, we performed a stability test 5 months after their fabrication. After the fifth month, sensors were tested for 10 days at fixed relative humidity (30%) and controlled temperature (30°C) every 6 hours. The aging drift was less than 3%RH for both sensors, which is within the time drift specification of the used climatic chamber.

For the other two designs, we have not measured their dynamic responses and either their time stabilities. As we have previously studied, the response time is directly related to the square value of the thickness of the sensitive layer [45]; as we have used the same substrate, the time response should be around 350 s. The time stability is directly associated with the sensing materials. Then, as all the materials are exactly the same, we can assume that the other sensors are expected to have a long lifetime.

331 4. Conclusions

332 In this work, we present the comparison between four different electrodes layouts: interdigitated electrodes (IDE), meandered electrodes, spiral electrodes, serpentine 333 334 electrodes (SRE). These designs are planar electrodes developed in only one surface of 335 the substrate. All these structures have been characterized as capacitive sensors, in 336 particular, as humidity sensors. We show a comparison in terms of numerical simulations 337 as well as experimental results. In order to measure the response of all the sensors to 338 moisture content, we have fabricated them by inkjet printing using a silver ink on a 339 polyimide substrate whose electrical permittivity is directly related to the relative 340 humidity.

341 We have studied their responses to RH in a frequency range from 100 kHz to 10 MHz.

Furthermore, we have looked into the thermal drift of each structure. In order to compareand contrast each response, we have normalized the values found taking into account the

area occupied by each structure.

- In terms of sensitivity to RH, all sensors show similar trends in frequency but the highest value is achieved by SRE, followed by spiral electrodes, IDE and meandered electrodes, in this order. Depending on the specific application and its requirements, we could choose a different configuration. For example, SRE and spiral electrodes should be selected when sensitivity is a critical factor. But these two designs are more complex than the other two and, therefore, their yield rates are lower than the other two configurations. Regarding IDE electrodes, it shows the best compromise between sensitivity a manufacturing yield.
- 352 Finally, meandered electrodes can be easily adapted to more complex designs [43].

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